

# ***Sensors, Cameras, and Systems for Industrial/Scientific Applications XI***

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*Editors*

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# Contents

vii *Conference Committee*

---

## SESSION 1 COLOR AND MULTISPECTRAL TECHNIQUES

---

- 7536 02 **Stacked color image sensor using wavelength-selective organic photoconductive films with zinc-oxide thin film transistors as a signal readout circuit** [7536-01]  
H. Seo, S. Aihara, M. Namba, T. Watabe, H. Ohtake, M. Kubota, N. Egami, NHK Science & Technology Research Labs. (Japan); T. Hiramatsu, T. Matsuda, M. Furuta, H. Nitta, T. Hirao, Kochi Univ. of Technology (Japan)
- 7536 03 **Improved sensitivity high-definition interline CCD using the KODAK TRUESENSE color filter pattern** [7536-02]  
J. DiBella, M. Andreghetti, A. Enge, W. Chen, T. Stanka, R. Kaser, Eastman Kodak Co. (United States)

---

## SESSION 2 SINGLE PHOTON DETECTION

---

- 7536 04 **Development of FOP-HARP imaging device** [7536-03]  
K. Miyakawa, NHK Engineering Services, Inc. (Japan); Y. Ohkawa, T. Matsubara, K. Kikuchi, S. Suzuki, K. Tanioka, M. Kubota, N. Egami, NHK Science & Technical Research Labs. (Japan); T. Atsumi, Hamamatsu Photonics K.K. (Japan); S. Matsushita, T. Konishi, Y. Sakakibara, Tsukuba Univ. (Japan); K. Hyodo, High Energy Accelerator Research Organization (Japan); Y. Katori, Y. Okamoto, Okamoto Optics Co., Ltd. (Japan)
- 7536 05 **Single-photon camera for high-sensitivity high-speed applications** [7536-04]  
F. Guerrieri, Politecnico di Milano (Italy); S. Tisa, Micro Photon Devices (Italy); A. Tosi, Politecnico di Milano (Italy); F. Zappa, Politecnico di Milano (Italy) and Micro Photon Devices (Italy)
- 7536 06 **Photon counting with an EMCCD** [7536-05]  
O. Daigle, Photon etc. (Canada) and Univ. de Montréal (Canada); S. Blais-Ouellette, Photon etc. (Canada)

---

## SESSION 3 LOW-LIGHT LEVEL

---

- 7536 07 **A 5.5Mpixel 100 frames/sec wide dynamic range low noise CMOS image sensor for scientific applications (Invited Paper)** [7536-06]  
B. Fowler, C. Liu, S. Mims, J. Balicki, W. Li, H. Do, J. Appelbaum, P. Vu, Fairchild Imaging (United States)
- 7536 08 **StarCam SG100: a high-update rate, high-sensitivity stellar gyroscope for spacecraft** [7536-07]  
A. Katake, C. Bruccoleri, StarVision Technologies, Inc. (United States)

---

**SESSION 4 APPLICATIONS**

---

- 7536 09 **Using the EMVA1288 standard to select an image sensor or camera** [7536-08]  
A. Darmont, Aphesa (Belgium)
- 7536 0A **High-speed document sensing and misprint detection in digital presses** [7536-09]  
G. Leseur, N. Meunier, G. Georgiadis, L. Huang, Stanford Univ. (United States); J. DiCarlo, Hewlett-Packard Labs. (United States); B. A. Wandell, P. B. Catrysse, Stanford Univ. (United States)
- 7536 0C **Fake fingerprint detection based on image analysis** [7536-11]  
S. Jin, Y. Bae, H. Maeng, H. Lee, Korea Polytechnic Univ. (Korea, Republic of)
- 7536 0D **Measurement of surface resistivity/conductivity of metallic alloys in aqueous solutions by optical interferometry techniques** [7536-12]  
K. Habib, Kuwait Institute for Scientific Research (Kuwait)
- 7536 0E **Carotenoid pixels characterization under color space tests and RGB formulas for mesocarp of mango's fruits cultivars** [7536-13]  
A. Y. Hammad, National Authority for Remote Sensing and Space Sciences (Egypt); F. S. E. S. Kassim, Horticultural Research Institute (Egypt)

---

**SESSION 5 MODELING**

---

- 7536 0F **Analyzing the impact of ISO on digital imager defects with an automatic defect trace algorithm** [7536-14]  
J. Leung, G. H. Chapman, Y. H. Choi, R. Thomas, Simon Fraser Univ. (Canada); Z. Koren, I. Koren, Univ. of Massachusetts (United States)
- 7536 0G **Enhanced sensitivity achievement using advanced device simulation of multifinger photo gate active pixel sensors** [7536-15]  
P. V. R. H. Kalyanam, G. H. Chapman, A. M. Parameswaran, Simon Fraser Univ. (Canada)
- 7536 0H **Modeling and measurements of MTF and quantum efficiency in CCD and CMOS image sensors** [7536-16]  
I. Djité, P. Magnan, M. Etribeau, Univ. de Toulouse (France); G. Rolland, S. Petit, Ctr. Nationales des Etudes Spatiales (France); O. Saint-pé, EADS Astrium (France)
- 7536 0J **Characterization and correction of dark current in compact consumer cameras** [7536-18]  
J. C. Dunlap, E. Bodegom, R. Widenhorn, Portland State Univ. (United States)

---

**SESSION 6 NOVEL IMAGING DEVICES AND APPLICATIONS**

---

- 7536 0K **Experiment and device simulation for photo-electron overflow characteristics on a pixel-shared CMOS image sensor using lateral overflow gate** [7536-19]  
S. Sakai, Y. Tashiro, L. Hou, S. Sugawa, Tohoku Univ. (Japan)
- 7536 0L **A new function of the optical-multiplex image-acquisition system** [7536-20]  
T. Narabu, Sony Corp. (Japan)

- 7536 0M **A 2.2M CMOS image sensor for high-speed machine vision applications** [7536-21]  
X. Wang, J. Bogaerts, G. Vanhorebeek, K. Ruythoren, B. Ceulemans, G. Lepage, P. Willems,  
G. Meynants, CMOSIS nv (Belgium)
- 7536 0N **Reducing crosstalk in vertically integrated CMOS image sensors** [7536-22]  
O. Skorka, D. Joseph, Univ. of Alberta (Canada)
- 7536 0O **A CMOS vision system on-chip with multicore sensory processing architecture for image analysis above 1,000F/s** [7536-23]  
A. Rodríguez-Vázquez, R. Domínguez-Castro, IMSE-CNM/CSIC, Univ. de Sevilla (Spain) and AnaFocus (Spain); F. Jiménez-Garrido, S. Morillas, AnaFocus (Spain)

---

**SESSION 7 INTERACTIVE PAPER SESSION**

---

- 7536 0Q **Electron-multiplying CCD astronomical photometry** [7536-26]  
A. Ferrero, Univ. College Dublin (Ireland) and Consejo Superior de Investigaciones Científicas (Spain); R. Felletti, L. Hanlon, Univ. College Dublin (Ireland); J. Campos, A. Pons, Consejo Superior de Investigaciones Científicas (Spain)
- 7536 0R **High-speed charge transfer pinned-photodiode for a CMOS time-of-flight range image sensor** [7536-27]  
H. Takeshita, T. Sawada, T. Iida, K. Yasutomi, S. Kawahito, Shizuoka Univ. (Japan)
- 7536 0S **A three-phase time-correlation image sensor using pinned photodiode active pixels** [7536-28]  
S. Han, T. Iwahori, T. Sawada, S. Kawahito, Shizuoka Univ. (Japan); S. Ando, The Univ. of Tokyo (Japan)
- 7536 0T **Dynamic range extension of an active pixel sensor by combining output signals from photodiodes with different sensitivities** [7536-29]  
J.-S. Kong, S.-H. Jo, K.-H. Choi, S.-H. Seo, P. Choi, J.-K. Shin, Kyungpook National Univ. (Korea, Republic of)
- 7536 0U **An efficient spectral-based calibration method for RGB white-balancing gains under various illumination conditions for cell-phone cameras** [7536-30]  
R. Safaee-Rad, Qualcomm Inc. (Canada); M. Aleksic, Qualcomm Inc. (United States)

*Author Index*



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**Ralf Widenhorn**, Portland State University (United States)
- 4 Applications  
**Ralf Widenhorn**, Portland State University (United States)

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**Valérie Nguyen**, CEA Leti MINATEC (France)
- 6 Novel Imaging Devices and Applications  
**Erik Bodegom**, Portland State University (United States)